

### 1. PART NO. EXPRESSION :

**S D I 3 2 1 6 1 8 - R 1 2 M F**

(a) (b) (c) (d)(e)

(a) Series code

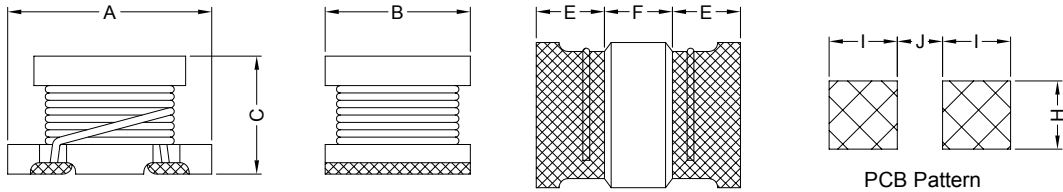
(b) Dimension code

(c) Inductance code : R12 = 0.12uH

(d) Tolerance code : J = ±5%, K = ±10%, M = ±20%

(e) F : Lead Free

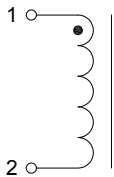
### 2. CONFIGURATION & DIMENSIONS :



Unit:m/m

A	B	C	E	F	H	I	J
3.2±0.3	1.6±0.2	1.8±0.3	0.7 Min.	0.7 Min.	1.5 Ref.	1.5 Ref.	1.0 Ref.

### 3. SCHEMATIC :



### 4. GENERAL SPECIFICATION :

- a) Ambient temp. : 20°C
- b) Operating temp. : -25°C to 85°C
- c) Rated current : Base on temp. rise &  $\Delta L/L0A=10\%$  Max.



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## 5. ELECTRICAL CHARACTERISTICS :

Part No.	Inductance ( uH )	Tolerance	Test Frequency ( Hz )	SRF ( MHz ) Min.	DCR ( Ω ) Max.	IDC ( mA ) Max.
SDI321618-R12□F	0.12	M	1M	250	0.112	970
SDI321618-R22□F	0.22	M	1M	250	0.140	850
SDI321618-R47□F	0.47	M	1M	180	0.210	700
SDI321618-1R0□F	1.0	M	1M	100	0.364	510
SDI321618-2R2□F	2.2	M	1M	50	0.533	430
SDI321618-4R7□F	4.7	K, M	1M	31	0.845	340
SDI321618-100□F	10	J, K	1M	20	1.690	230
SDI321618-220□F	22	J, K	1M	14	3.900	160
SDI321618-470□F	47	J, K	1M	10	10.40	100
SDI321618-101□F	100	J, K	1M	7.0	15.60	80

Tolerance code :

- : J = ±5%
- K = ±10%
- M = ±20%



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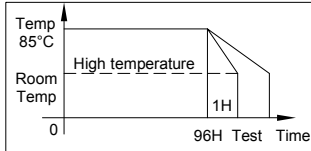
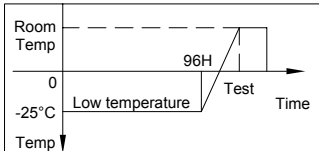
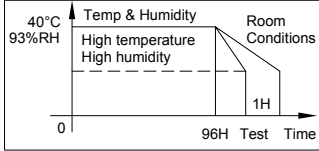
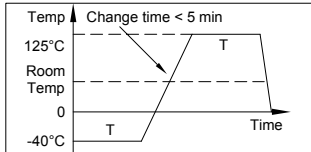
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## 6. RELIABILITY AND TEST CONDITION :

ITEM	PERFORMANCE	TEST CONDITION
Environmental Tests		
High Temperature Storage Test  Reference documents: MIL-STD-202G Method 108A	1. No case deformation or change in appearance. 2. $\Delta L/L \leq 30\%$ (Closed Magnetic Circuit) $\Delta L/L \leq 10\%$ 3. $\Delta Q/Q \leq 30\%$ 4. $\Delta DCR/DCR \leq 10\%$	Temperature : $85 \pm 2^\circ\text{C}$ Time : $96 \pm 2$ hours Tested after 1 hour (less than 2 hours) at room temperature  
Low Temperature Storage Test  Reference documents: IEC 68-2-1A 6.1 6.2	1. No case deformation or change in appearance. 2. $\Delta L/L \leq 30\%$ (Closed Magnetic Circuit) $\Delta L/L \leq 10\%$ 3. $\Delta Q/Q \leq 30\%$ 4. $\Delta DCR/DCR \leq 10\%$	Temperature : $-25 \pm 2^\circ\text{C}$ Time : $96 \pm 2$ hours Tested after 1 hour (less than 2 hours) at room temperature  
Humidity Test  Reference documents: MIL-STD-202G Method 103B	1. No case deformation or change in appearance. 2. $\Delta L/L \leq 30\%$ (Closed Magnetic Circuit) $\Delta L/L \leq 10\%$ 3. $\Delta Q/Q \leq 30\%$ 4. $\Delta DCR/DCR \leq 10\%$	Dry oven at temperature of $40 \pm 5^\circ\text{C}$ for 24 hours Measured after 24 hours Exposure : Temperature : $40 \pm 2^\circ\text{C}$ , Humidity : $93 \pm 3\%$ RH, Time : $96 \pm 2$ hours Tested while the specimens are still in the chamber Tested after 1 hour (less than 2 hours) at room temperature  
Thermal shock test  Reference documents: MIL-STD-202G Method 107G	1. No case deformation or change in appearance. 2. $\Delta L/L \leq 30\%$ (Closed Magnetic Circuit) $\Delta L/L \leq 10\%$ 3. $\Delta Q/Q \leq 30\%$ 4. $\Delta DCR/DCR \leq 10\%$ T : weight $\leq 28\text{g}$ : 15 Min. $28\text{g} \leq \text{weight} \leq 136\text{g}$ : 30 Min.	Conditions of 1 cycle : Step 1 : $-40^\circ\text{C}$ for T time Step 2 : $125^\circ\text{C}$ for T time Total : 20 cycles  
Physical Characteristics Tests		
Solderability Test  Reference documents: MIL-STD-202G Method 208H IPC J-STD-002B	More than 95% of terminal electrode should be covered with solder.	Solder temperature : $245 \pm 5^\circ\text{C}$ Dip time : 5 secs. Solder : Sn(63)/Pb(37) Flux : rosin flux



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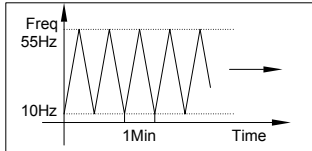
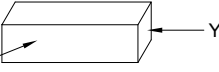
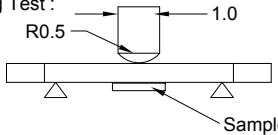
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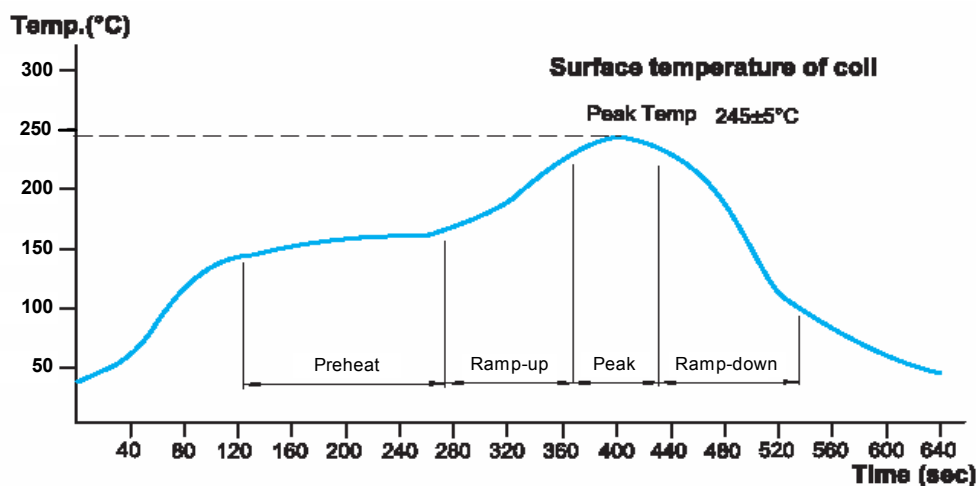


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## 6. RELIABILITY AND TEST CONDITION :

ITEM	PERFORMANCE	TEST CONDITION												
Heat Endurance of Reflow Soldering  Reference documents: IPC J-STD-020B	1. No case deformation or change in appearance. 2. $\Delta L/L \leq 30\%$ (Closed Magnetic Circuit) $\Delta L/L \leq 10\%$ 3. $\Delta Q/Q \leq 30\%$ 4. $\Delta DCR/DCR \leq 10\%$	Refer to reflow curve. No. of cycle : 3 Peak temp. : $245 \pm 5^\circ\text{C}$												
Vibration Test  Reference documents: MIL-STD-202G Method 201A	1. No case deformation or change in appearance. 2. $\Delta L/L \leq 30\%$ (Closed Magnetic Circuit) $\Delta L/L \leq 10\%$ 3. $\Delta Q/Q \leq 30\%$ 4. $\Delta DCR/DCR \leq 10\%$	Frequency : 10~55Hz Amplitude : 0.75mm Directions & times : X, Y, Z directions for 2 hours. A period of 2 hours in each of 3 mutually perpendicular directions (Total 6 hours).  												
Drop Test  Reference documents: MIL-STD-202G Method 203C	1. No case deformation or change in appearance. 2. $\Delta L/L \leq 30\%$ (Closed Magnetic Circuit) $\Delta L/L \leq 10\%$ 3. $\Delta Q/Q \leq 30\%$ 4. $\Delta DCR/DCR \leq 10\%$	Drop from a height of 1m with $981\text{m/s}^2$ (100G) altitude (1 angle, 1 ridge and 2 surface orientations)												
Terminal Strength Push Test  Reference documents: JIS C 5321:1997	Pulling Test : A : Sectional area of terminal <table border="1" data-bbox="467 1070 852 1193"> <thead> <tr> <th></th> <th>Force</th> <th>Time (sec)</th> </tr> </thead> <tbody> <tr> <td><math>A \leq 8\text{mm}^2</math></td> <td><math>\geq 5\text{N}</math></td> <td>30</td> </tr> <tr> <td><math>8\text{mm}^2 &lt; A \leq 20\text{mm}^2</math></td> <td><math>\geq 10\text{N}</math></td> <td>10</td> </tr> <tr> <td><math>20\text{mm}^2 &lt; A</math></td> <td><math>\geq 20\text{N}</math></td> <td>10</td> </tr> </tbody> </table> Bending Test : The terminal electrode & the dielectric must not be damaged by the forces applied on the right conditions.		Force	Time (sec)	$A \leq 8\text{mm}^2$	$\geq 5\text{N}$	30	$8\text{mm}^2 < A \leq 20\text{mm}^2$	$\geq 10\text{N}$	10	$20\text{mm}^2 < A$	$\geq 20\text{N}$	10	Bend PCB at middle point, the deflection shall be 2mm. Pulling Test :  Bending Test :  Sample
	Force	Time (sec)												
$A \leq 8\text{mm}^2$	$\geq 5\text{N}$	30												
$8\text{mm}^2 < A \leq 20\text{mm}^2$	$\geq 10\text{N}$	10												
$20\text{mm}^2 < A$	$\geq 20\text{N}$	10												

### Reflow Curve



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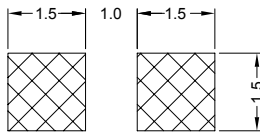
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## 7. SOLDERING AND MOUNTING :

### 7-1. Recommended PC Board Pattern



### 7-2. Soldering

Mildly activated rosin fluxes are preferred. The minimum amount of solder can lead to damage from the stresses caused by the difference in coefficients of expansion between solder, chip and substrate. Our terminations are suitable for all wave and re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

#### 7-2.1 Solder Re-flow :

Recommended temperature profiles for re-flow soldering in Figure 1.

#### 7-2.2 Solder Wave :

Wave soldering is perhaps the most rigorous of surface mount soldering processes due to the steep rise in temperature seen by the circuit when immersed in the molten solder wave, typical at 240°C. Due to the risk of thermal damage to products, wave soldering of large size products is discouraged. Recommended temperature profile for wave soldering is shown in Figure 2.

#### 7-2.3 Soldering Iron (Figure 2) :

Products attachment with soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

Note :

- Preheat circuit and products to 150°C.
- 280°C tip temperature (max)
- Never contact the ceramic with the iron tip
- 1.0mm tip diameter (max)
- Use a 20 watt soldering iron with tip diameter of 1.0mm
- Limit soldering time to 3 secs.

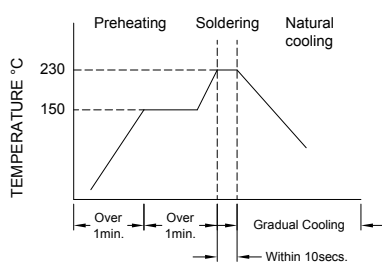


Figure 1. Re-flow Soldering

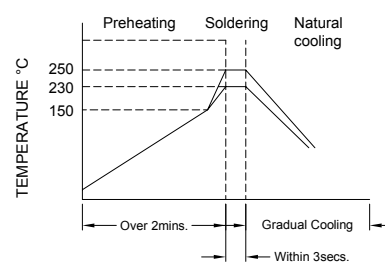


Figure 2. Wave Soldering

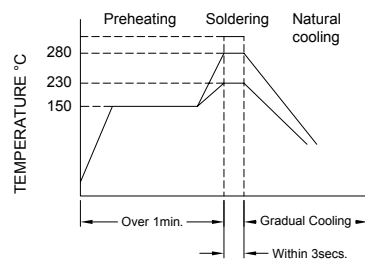


Figure 3. Hand Soldering



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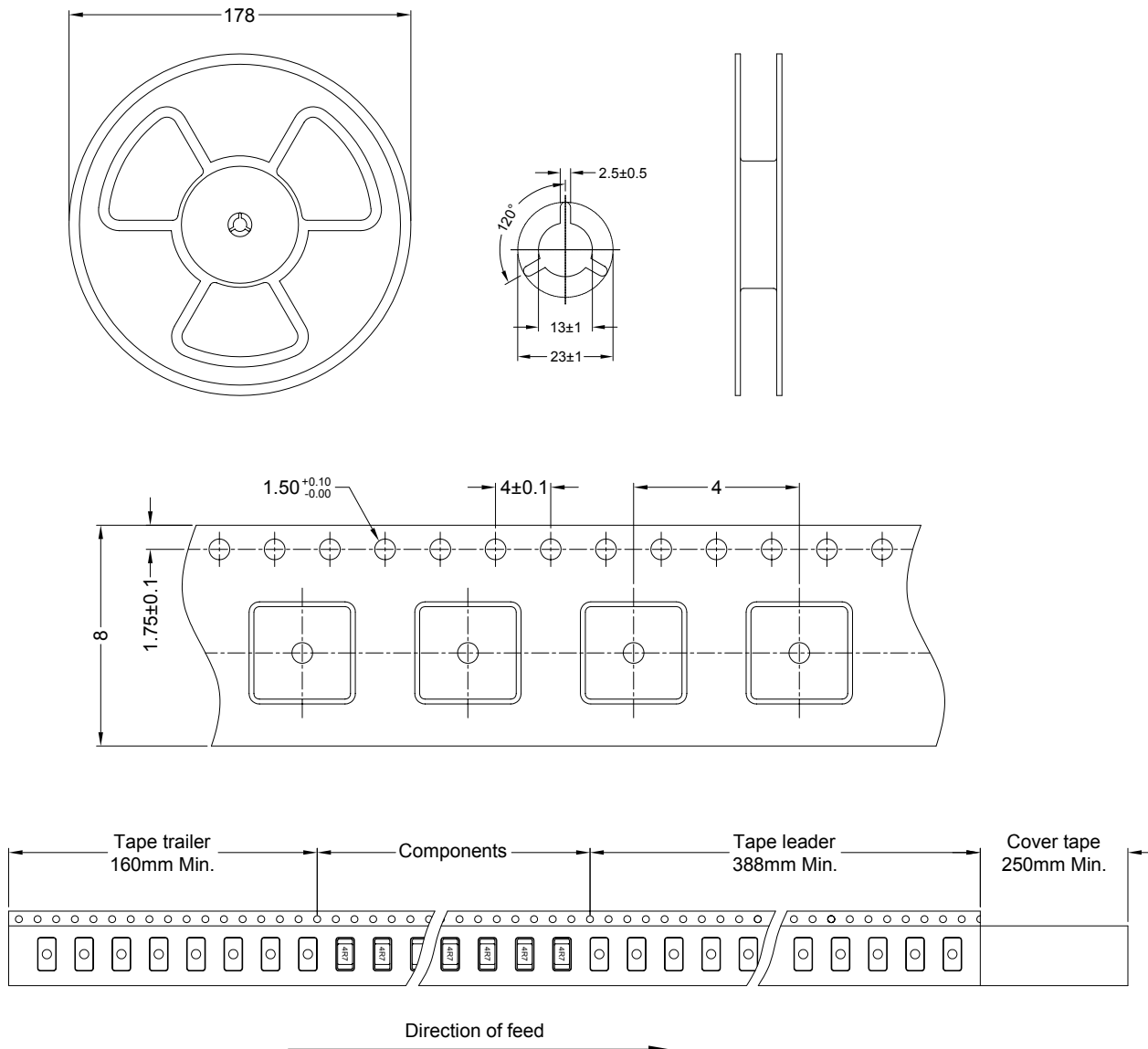
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## 8. PACKAGING INFORMATION : ( Unit : mm )

### 8-1. Reel & Tape Dimension



### 8-2. Quantity & G.W. per package

SERIES	INNER : REEL		OUTER : CARTON		
	Q'TY (PCS)	G.W. (Kg)	Q'TY (PCS)	G.W. (Kg)	SIZE (cm)
SDI321618	2000	0.13	120000	12	39 x 39 x 23



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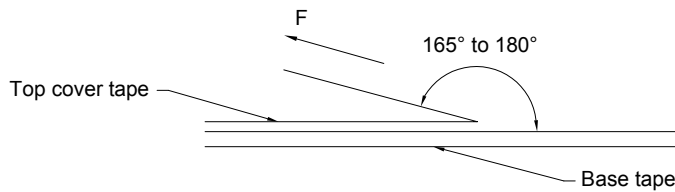
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### 8-3. Tearing Off Force



The force for tearing off cover tape is 10 to 60 grams in the arrow direction.

### Application Notice

#### 1. Storage Conditions :

To maintain the solderability of terminal electrodes :

- a) Temperature and humidity conditions : Less than 40°C and 70% RH.
- b) Recommended products should be used within 6 months from the time of delivery.
- c) The packaging material should be kept where no chlorine or sulfur exists in the air.

#### 2. Transportation :

- a) Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- b) The use of tweezers or vacuum pick up is strongly recommended for individual components.
- c) Bulk handling should ensure that abrasion and mechanical shock are minimized.



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